



Material Content Data Sheet



Sales Product Name				BGSX 24MU16 E6327		Issued		4. July 2019	
MA#				MA004134278					
Package				PG-ULGA-16-1		Weight*		5.33 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.564	10.58	10.58	105841	105841	
bumps	non noble metal	copper	7440-50-8	0.022	0.40	0.40	4050	4050	
encapsulation	organic material	carbon black	1333-86-4	0.026	0.49		4924		
	organic material	phenol formaldehyde resin	9003-35-4	0.131	2.46		24619		
	plastics	epoxy resin	-	0.367	6.89		68933		
	inorganic material	amorphous silica	7631-86-9	0.787	14.77		147713		
	inorganic material	silicondioxide	60676-86-0	1.311	24.66	49.27	246187	492376	
leadfinish	noble metal	palladium	7440-05-3	0.000	0.01		55		
	noble metal	gold	7440-57-5	0.000	0.01		88		
	non noble metal	nickel	7440-02-0	0.009	0.16	0.18	1610	1753	
substrate	inorganic material	aluminiumhydroxide	21645-51-2	0.278	5.21		52122		
	plastics	epoxy bismaleimide triazine resin	-	0.319	5.98		59844		
	inorganic material	glass fibre	-	0.432	8.11		81078		
	non noble metal	copper	7440-50-8	0.853	16.01	35.31	160142	353186	
plating	noble metal	palladium	7440-05-3	0.000	0.00		45		
	noble metal	gold	7440-57-5	0.000	0.01		73		
	non noble metal	nickel	7440-02-0	0.007	0.13	0.14	1331	1449	
solder	noble metal	silver	7440-22-4	0.000	0.00		31		
	non noble metal	nickel	7440-02-0	0.002	0.03		308		
	non noble metal	tin	7440-31-5	0.008	0.15		1541		
	non noble metal	copper	7440-50-8	0.023	0.43	0.61	4284	6164	
ubm	non noble metal	titanium	7440-32-6	0.000	0.00		6		
	non noble metal	copper	7440-50-8	0.000	0.00	0.00	46	52	
solder resists	inorganic material	magnesiumsilicate	1343-88-0	0.015	0.28		2810		
	plastics	epoxy resin	-	0.047	0.88		8782		
	inorganic material	silicondioxide	60676-86-0	0.049	0.91		9134		
	inorganic material	bariumsulfate	7727-43-7	0.077	1.44	3.51	14403	35129	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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